

Product / Process Change Notice

Parts Affected:

Chip process CPS041, Silicon Controlled Rectifiers.

Part Numbers Affected:

CS92B	2N5060
CS92D	2N5061
CS92M	2N5062
CS92N	2N5063
	2N5064

Extent of Change:

The CPS041 wafer process has been discontinued and replaced with the CPS043 wafer process. There have been slight changes in die size that do not negatively impact electrical performance.

Reason for Change:

An alternate wafer foundry was approved for this process in order to enhance capacity and mitigate any future disruption to product supply.

Effect of Change:

This change does not affect the electrical characteristics of the product. Updated curves to be provided upon completion of qualification.

Qualification:

Standard evaluation and qualification testing is in-process.

Effective Date of Change:

Existing inventory will be shipped until depleted.

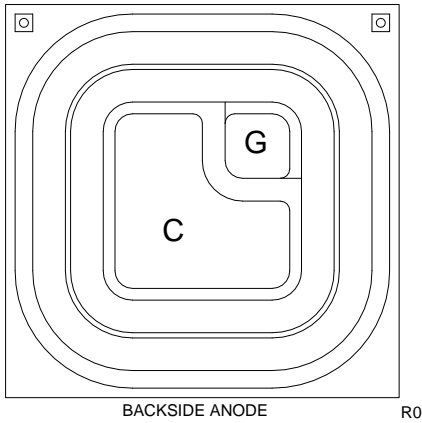
Sample Availability:

Please contact your salesperson or manufacturer's representative for samples.

PCN #157
Notification Date:
January 12, 2017

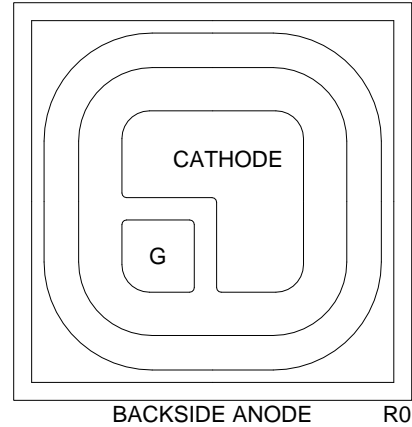
Figures:

Figure 1: CPS041 Chip Geometry (Discontinued)



Wafer Diameter:	4 inch
Die Size:	41 x 41 mils
Die Thickness:	8.7 mils
Bond Pad Size (Cathode):	18 x 8 mils
Bond Pad Size (Gate):	7.1 x 7.1 mils
Topside Metal:	Al (45,000Å)
Backside Metal:	Al/Mo/Ni/Ag (20,000Å/5,000Å/5,000Å/2,000Å)

Figure 2: CPS043 Chip Geometry (Replacement)



Wafer Diameter:	4 inch
Die Size:	43.3 x 43.3 mils
Die Thickness:	8.3 mils
Bond Pad Size (Cathode):	19.7x 9.5 mils
Bond Pad Size (Gate):	7.9 x 7.9 mils
Topside Metal:	Al (30,000Å)
Backside Metal:	Al/Mo/Ni/Ag (20,000Å/5,000Å/5,000Å/2,000Å)



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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	